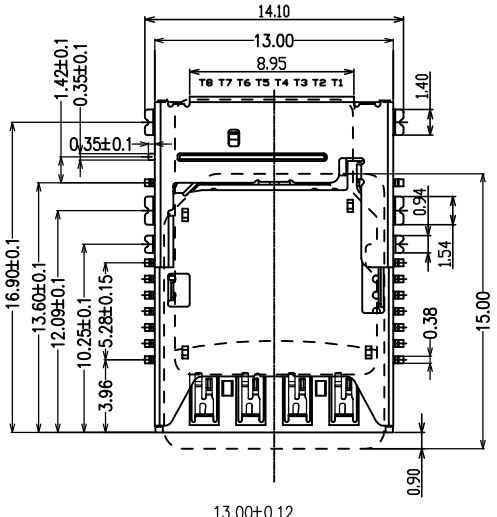
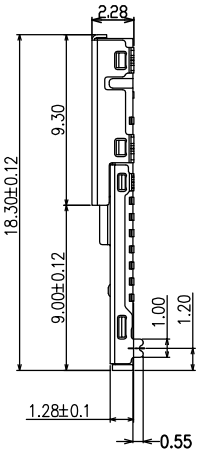
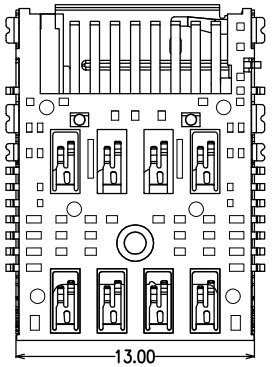
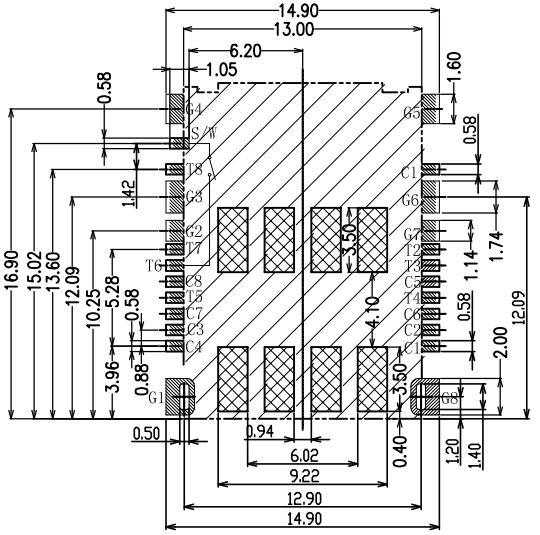
由 Autodesk 教育版产品制作

REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2015/12/29



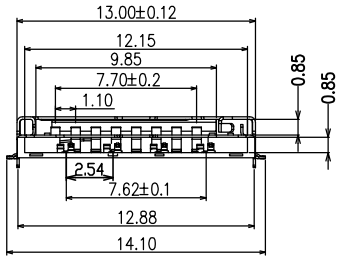


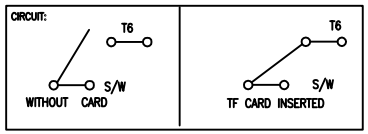


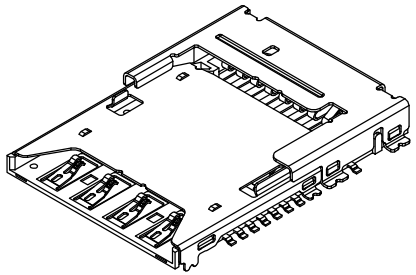


NO PATTERN AREA
NO CIRCUIT AREA
SOLDER AREA

P.C.B LAYOUT
(TOLERANCE±0.05)







NOTE:

一.材质及电镀方式（MATERIAL AND FINISH）

1.塑胶（HOUSING):LCP,
UL 94V-0 , COLOR:WHITE

2.端子（CONTACT):COPPER ALLOY
GOLD FLASH PLATING ON CONTACT AREA,
GOLD FLASH PLATING ON SOLDER TAILS
50u" NICKEL UNDER PLATING OVER ALL

3.铁壳（SHELL):SUS304-3/4H
40u" NICKEL UNDER PLATING OVER ALL

二.机械特性（MECHANICAL CHARACTERISTICS ㄘ

1.脣 薯卩Insertion Force):2.0Kgf Max
2.拔出力（Withdrawal Force):0.1Kgf Min
3.耐久性(Durability):5000次

三.电气特性

1.额定电流（Current rating):1.0A AC/DC
2.接触电阻（Contact resistance):100mΩ MAX
3.绝缘电阻（Insulation resistance):500MΩ MIN
4.适用温度（Operating temperature):-20℃～65℃

TF CARD PIN ASSIGNMENT

PIN NO.	PIN ASSIGNMENT
T1	DAT2
T2	CD/DAT3 [2]
T3	CMD
T4	VDD
T5	CLK
T6	VSS
T7	DAT0
T8	DAT1

SIM pin assignment	
	Name
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

GENERAL TOLERANCE		DWG NO.	JYSA1205-001	APPD:	WIND	Scale	1:1
		Title	MICRO SIM+ TF 二合一卡座(前插后贴)	CHKD:		UNIT	mm
.X±0.5	.x°±2°			DR:			
.XX±0.2	.xx°±1°	Part NO.	JYS-SIM228-108	Date	2015/12/29		
.XXX±0.1							
SHEET	1/1						

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